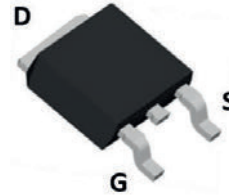
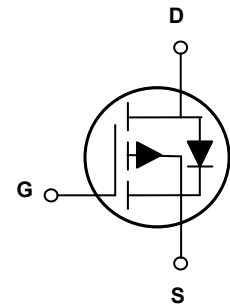


Main Product Characteristics

BV_{DSS}	-40V
$R_{DS(ON)}$	27m Ω (Max.)
I_D	-32A



TO-252 (DPAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFD4027 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V _{DS}	-40	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous (T _C =25°C), V _{GS} =10V ¹	I _D	-32	A
Drain Current-Continuous (T _C =100°C), V _{GS} =10V ¹		-26	A
Drain Current-Pulsed ²	I _{DM}	-128	A
Pulsed Source Current (Body Diode) ²	I _{SM}	-128	A
Power Dissipation (T _C =25°C) ³	P _D	38	W
Single Pulse Avalanche Energy (L=0.5mH)	E _{AS}	100	mJ
Single Pulse Avalanche Current (L=0.5mH)	I _{AS}	20	A
Thermal Resistance, Junction-to-Ambient (t ≤ 10s) ⁴	R _{θJA}	62	°C/W
Thermal Resistance, Junction-to-Case	R _{θJC}	3.29	°C/W
Operating Junction Temperature Range	T _J	-55 To +150	°C
Storage Temperature Range	T _{STG}	-55 To +150	°C

Electrical Characteristics (T_A=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-40	-	-	V
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	-1	μA
Drain-to-Source Leakage Current		V _{DS} =-40V, V _{GS} =0V, T _J =125°C	-	-	-50	μA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250μA	-1.1	-	-2.5	V
Drain Static-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-8A	-	22	27	mΩ
		V _{GS} =-4.5V, I _D =-4A	-	27	39	mΩ
Dynamic and Switching Characteristics						
Total Gate Charge	Q _g	V _{DD} =-20V, I _D =-5A, V _{GS} =-10V	-	26	-	nC
Gate-Source Charge	Q _{gs}		-	6.6	-	
Gate-Drain Charge	Q _{gd}		-	3.6	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} =-20V, R _G =3Ω, V _{GS} =-10V, I _D =-5A	-	7.7	-	nS
Rise Time	t _r		-	4.1	-	
Turn-Off Delay Time	t _{d(off)}		-	29	-	
Fall Time	t _f		-	6.0	-	
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V, F=1MHz	-	1421	-	pF
Output Capacitance	C _{oss}		-	128	-	
Reverse Transfer Capacitance	C _{rss}		-	88	-	
Gate Resitance	R _g	F=1MHz	-	9.8	-	Ω
Source-Drain Ratings and Characteristics						
Maximum Body-Diode Continuous Current	I _S	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	-32	A
Maximum Body-Diode Pulse Current	I _{SM}		-	-	-128	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-5A, T _J =25°C	-	-1.0	-1.2	V
Reverse Recovery Time	T _{rr}	I _F =-5A, di/dt=100A/ μs, T _J =25°C	-	35	-	nS
Reverse Recovery Charge	Q _{rr}		-	39	-	nC

Notes:

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. The power dissipation P_D is based on max. junction temperature, using junction-to-case thermal resistance.
4. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

Typical Electrical and Thermal Characteristic Curves

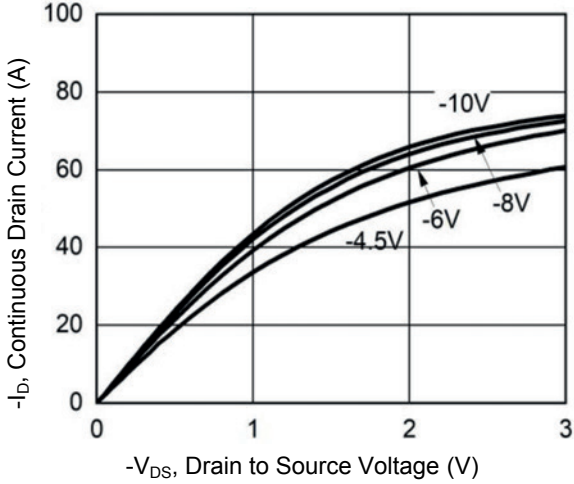


Figure 1. Typical Output Characteristics

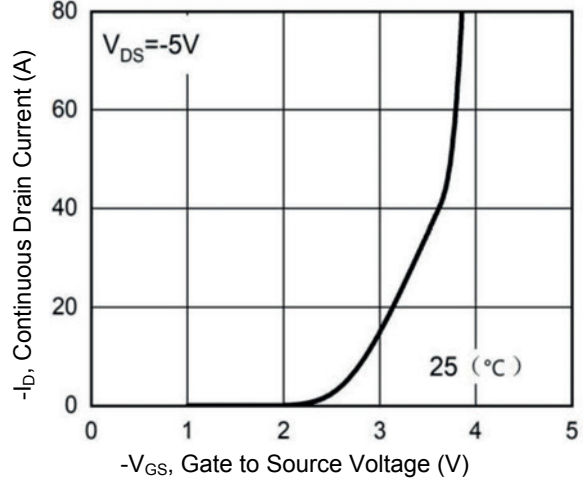


Figure 2. Transfer Characteristics

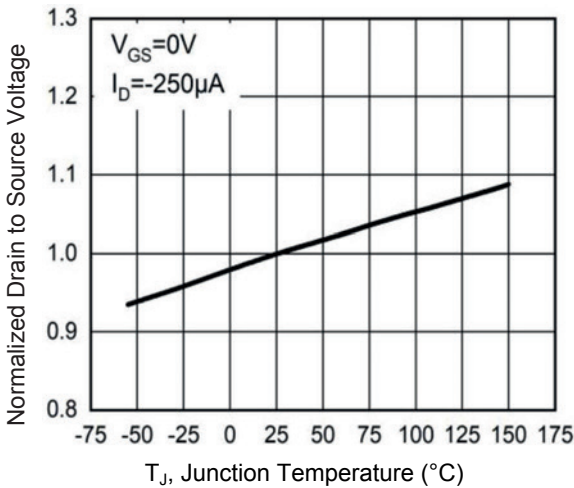


Figure 3. Normalized BV_{DS} vs. T_J

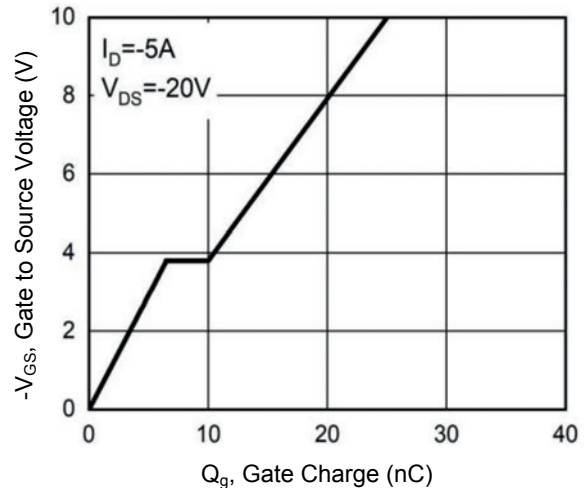


Figure 4. Gate Charge Characteristics

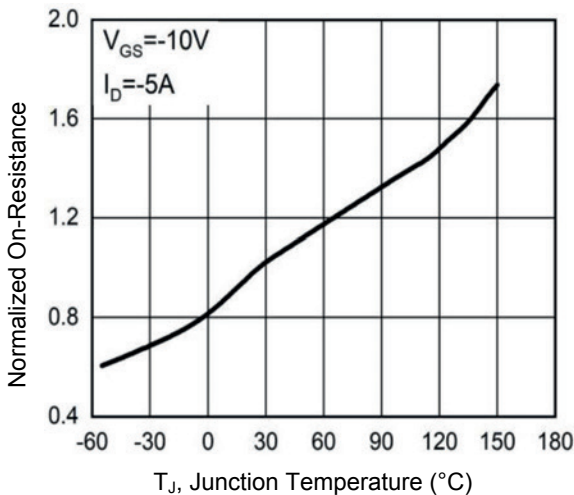


Figure 5. Normalized $R_{DS(ON)}$ vs. T_J

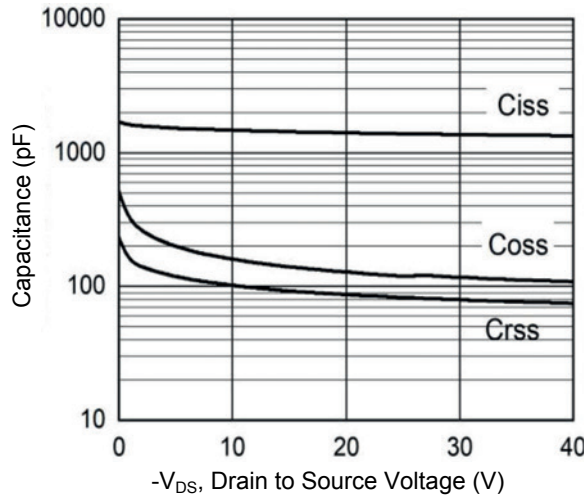


Figure 6. Capacitance Characteristics

Typical Electrical and Thermal Characteristic Curves

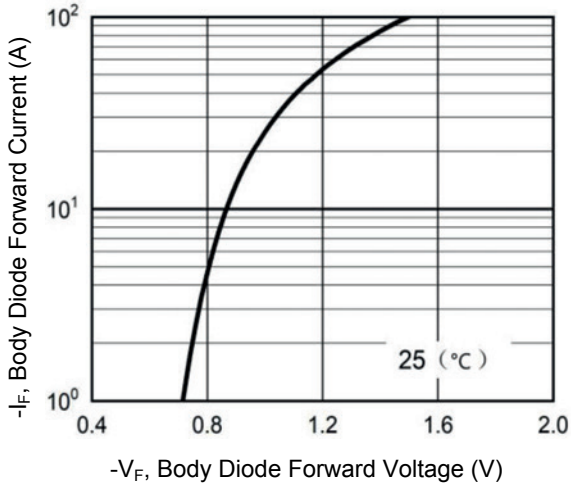


Figure 7. Body Diode Characteristics

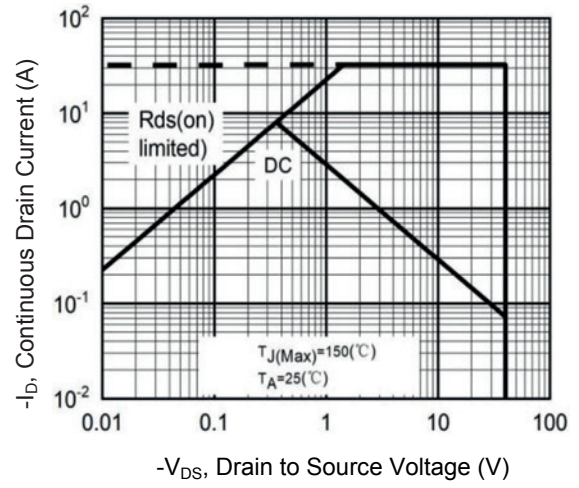
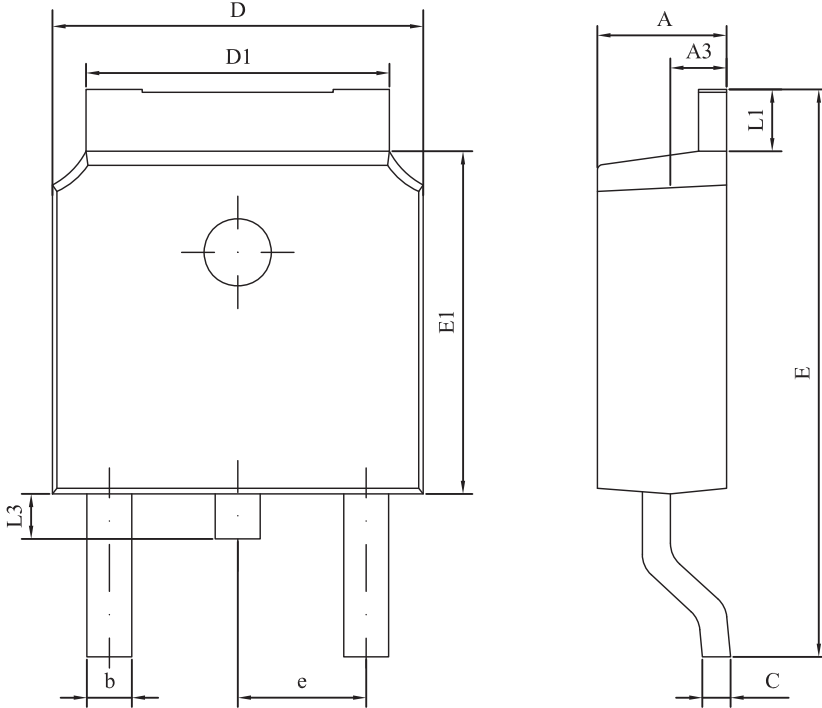


Figure 8. Maximum Safe Operation Area

Package Outline Dimensions TO-252(DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.15	2.40	0.085	0.094
A3	0.90	1.10	0.035	0.043
b	0.50	0.90	0.020	0.035
C	0.40	0.65	0.016	0.026
D	6.30	6.90	0.248	0.272
D1	4.95	5.50	0.195	0.217
E	9.40	10.41	0.370	0.410
E1	5.90	6.30	0.232	0.248
e	2.286 BSC		0.090 BSC	
L1	0.89	1.27	0.035	0.050
L3	0.60	1.10	0.024	0.043

Order Information

Device	Package	Marking	Carrier	Quantity
GSFD4027	TO-252 (DPAK)	D4027	Tape & Reel	2,500pcs / Reel

For more information, please contact us at: inquiry@goodarksemi.com